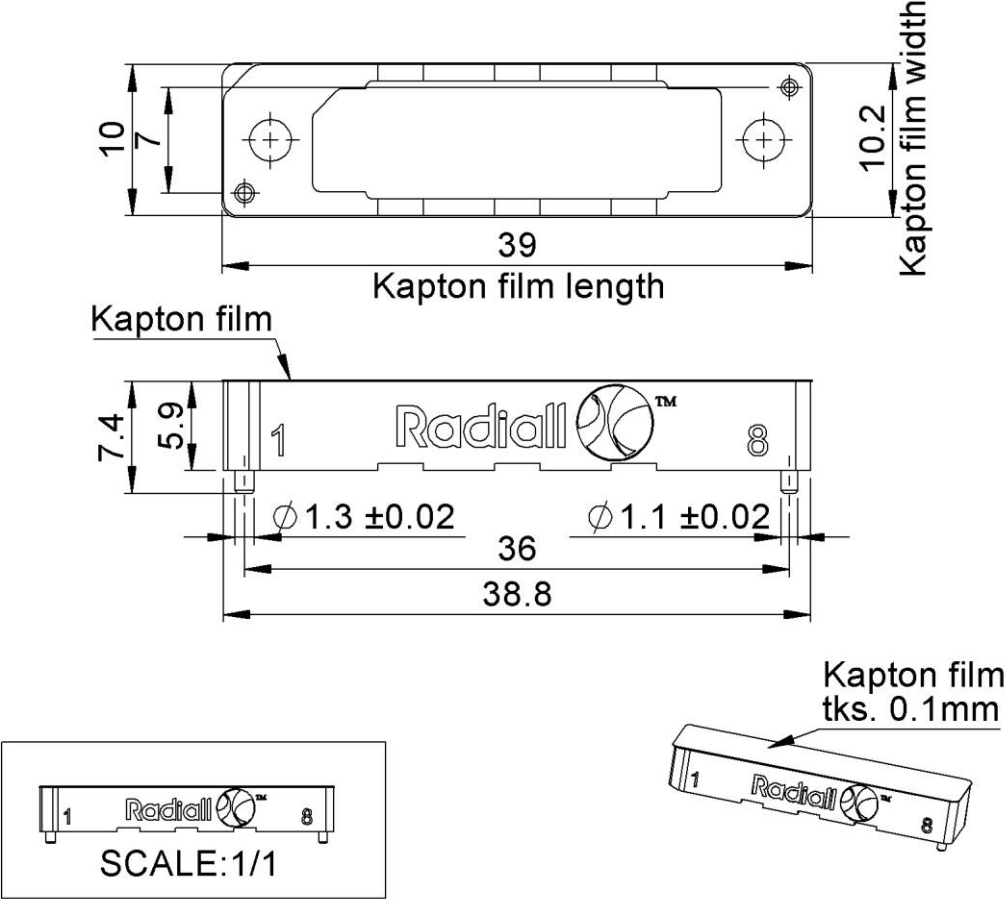
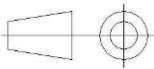


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All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	COPPER ALLOY	GOLD
Center contact		
Outer contact		
Insulator		
Gasket		
Others parts	KAPTON	
-	-	-
-	-	-

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## PACKAGING

Standard	Unit	Other
<b>500</b>	<b>Contact us</b>	<b>Contact us</b>

## ELECTRICAL CHARACTERISTICS

Impedance		<b>50</b>	$\Omega$
Frequency		<b>DC-67</b>	GHz
VSWR	<b>NA</b>	<b>+</b>	<b>0.0000</b> x F(GHz) Maxi
Insertion loss		<b>NA</b>	$\sqrt{F}$ (GHz) dB Maxi
RF leakage	- (	<b>NA</b>	- F(GHz)) dB Maxi
Voltage rating		<b>NA</b>	Veff Maxi
Dielectric withstanding voltage		<b>NA</b>	Veff mini
Insulation resistance		<b>NA</b>	M $\Omega$ mini

## MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	<b>NA</b>	N mini
Axial force – Opposite end	<b>NA</b>	N mini
Torque	<b>NA</b>	N.cm mini

Recommended torque		
Mating	<b>NA</b>	N.cm
Panel nut	<b>NA</b>	N.cm

Mating life	<b>100</b>	Cycles mini
Nominal Weight	<b>8.5200</b>	g
(Add +15% for max weight)		

## ENVIRONMENTAL

Operating temperature	<b>0/+85</b>	°C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

## SPECIFICATION

## OTHER CHARACTERISTICS

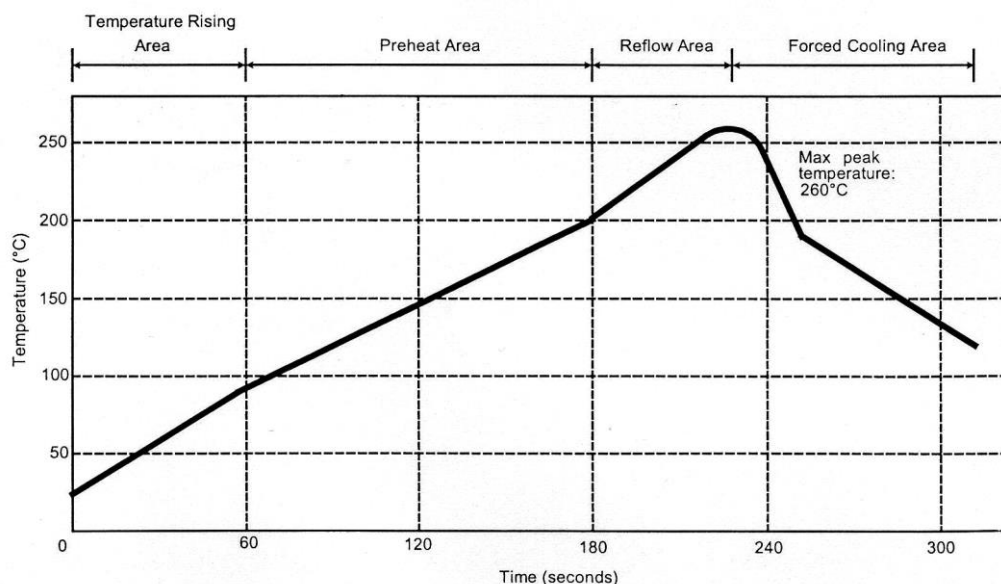
Assembly instruction:

Others:

## SOLDER PROCEDURE

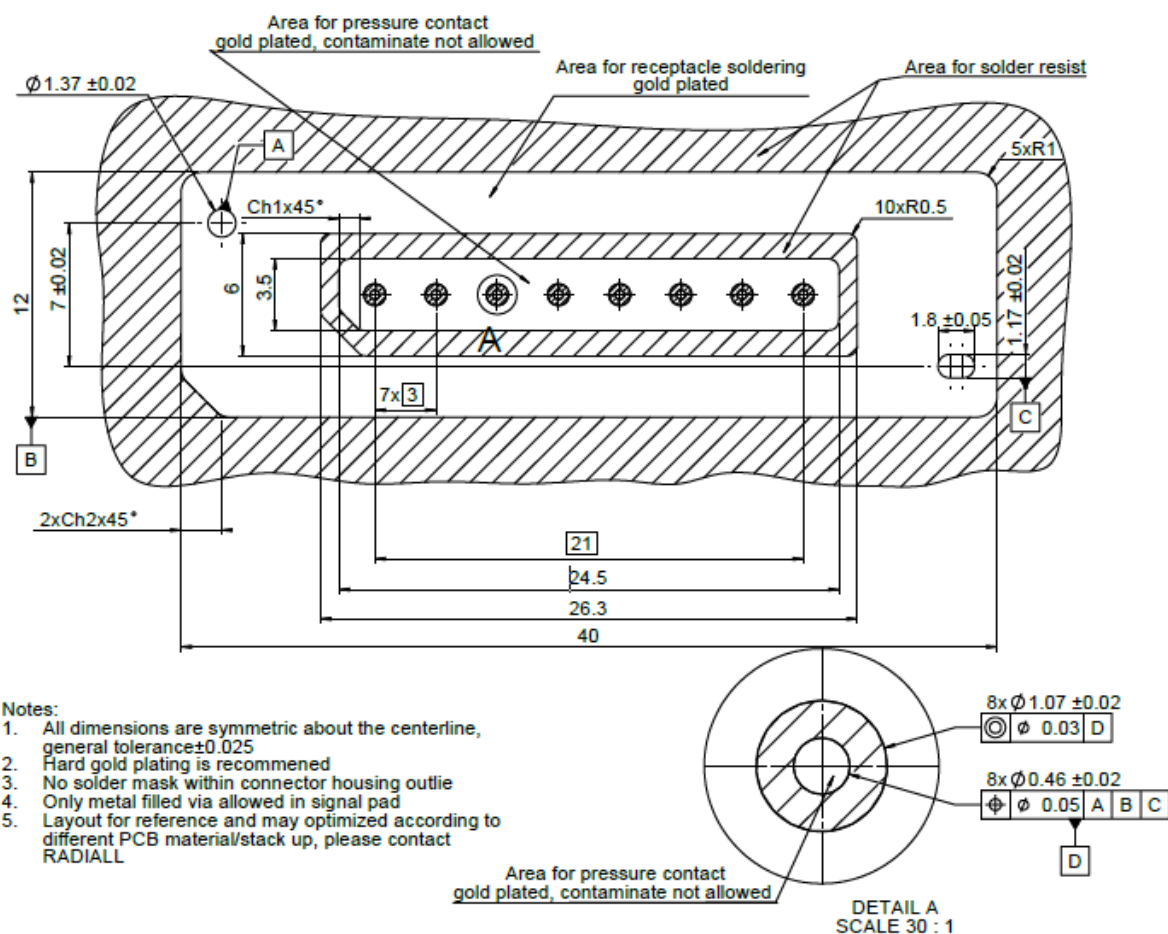
1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microns ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

## TEMPERATURE PROFILE



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

## PCB FOOT PRINT



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## TAPE AND REEL

